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Notification Number:	20260825002.0	Notification Issued	August 31, 2026
Datasheet for LMR60410-Q1, LMR60406-Q1, LMR60430-Q1, LMR61440-Q1, LMR60440-Q1, LMR60460-Q1			
Change Type(s)	Data Sheet/Electrical Specification		
ZVEI ID	SEM-DS-02		

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



LMR60410-Q1

SNAS870C – JULY 2025 – REVISED AUGUST 2026

Changes from Revision B (March 2026) to Revision C (August 2026)	Page
• Added MINT 1 switcher terminology in the document title, <i>Features</i> , and the <i>Description</i> sections.....	1
• Added more pin-to-pin devices in the <i>Features</i> section.....	1
• Changed the standby current from 5µA to 3.5µA in the <i>Features</i> section.....	1
• Updated device status for LMR604103SBRAKRQ1, LMR604103BRAKRQ1, and LMR604105BRAKRQ1 to Production Data in the <i>Device Comparison</i> section.....	3
• Deleted part numbers LMR604103RAKRQ1 and LMR604105RAKRQ1 from the <i>Device Comparison</i> section	3
• Updated <i>Soft Start and Recovery from Dropout</i> to clarify the section for recovery from dropout.....	12
• Updated SYNC mode description to clarify the external clock frequency range in <i>MODE/SYNC Pin Control</i>	13
• Updated <i>Inductor Selection</i> guidance to include recommended design margins for subharmonic stability.....	22

Changes from Revision A (February 2026) to Revision B (August 2026)	Page
• Added MINT 1 switcher terminology in the document title, <i>Features</i> , and the <i>Description</i> sections.....	1
• Added more pin-to-pin devices in the <i>Features</i> section.....	1
• Changed the standby current from 5µA to 3.5µA in the <i>Features</i> section.....	1
• Added the ™ symbol to HotRod in <i>Description</i> and <i>Overview</i>	1
• Updated device status for LMR604065SBRAKRQ1, LMR604063BRAKRQ1, and LMR604065BRAKRQ1 to Production Data in the <i>Device Comparison</i> section.....	3
• Deleted part numbers LMR604063SRAKRQ1, LMR604063RAKRQ1, and LMR604065RAKRQ1 from the <i>Device Comparison</i> section.....	3
• Updated <i>Soft Start and Recovery from Dropout</i> to clarify the section for recovery from dropout.....	12
• Updated SYNC mode description to clarify the external clock frequency range in <i>MODE/SYNC Pin Control</i>	13
• Updated <i>Inductor Selection</i> guidance to include recommended design margins for subharmonic stability.....	22

Changes from Revision D (August 2026) to Revision E (August 2026)	Page
• Deleted Advance Information table note from RBM package and added QFN-11 in the <i>Description</i> section....	1
• Changed orderable part numbers PLMR604303SRBMRQ1 and PLMR604305SRBMRQ1 from preview status to LMR604303SRBMRQ1 and LMR604305SRBMRQ1 release status in the <i>Device Comparison</i> section.....	3

Changes from Revision C (June 2026) to Revision D (August 2026)	Page
• Changed orderable part number PLMR604304SBRAKRQ1 from preview status to LMR604304SBRAKRQ1 release status in the <i>Device Comparison</i> section	3
• Updated <i>Inductor Selection</i> guidance to include recommended design margins for subharmonic stability.....	22

Changes from Revision B (January 2026) to Revision C (June 2026)	Page
• Added more pin compatible devices to the <i>Features</i> list.....	1
• Deleted ZEN 1 switcher terminology and added MINT 1 switcher terminology in the document title and the <i>Features</i> list.....	1
• Added the RBM package throughout the document.....	1
• Added part number PLMR604304SBRAKRQ1, PLMR604303SRBMRQ1, and PLMR604305SRBMRQ1 to the <i>Device Comparison</i> table.....	3
• Changed from BST to BOOT in the <i>Absolute Maximum Ratings</i> table.....	5
• Changed minimum storage temperature from –65°C to –55°C in the <i>Absolute Maximum Ratings</i> table.....	5
• Updated <i>Thermal Information</i> table to include RBM package metrics.....	5
• Updated <i>Soft Start and Recovery from Dropout</i> to clarify the section for recovery from dropout.....	12
• Updated SYNC mode description to clarify the external clock frequency range in <i>Section 7.3.4</i>	13
• Added recommended layout example for RBM package.....	35
• Updated the device naming nomenclature to include the RBM package.....	36

Changes from Revision * (June 2026) to Revision A (August 2026)	Page
• Changed part number PLMR614405SRAKRQ1 from Advance Information status to LMR614405SRAKRQ1 release status.....	3
• Updated <i>Soft Start and Recovery from Dropout</i> to clarify the section for recovery from dropout.....	12
• Updated SYNC mode description to clarify the external clock frequency range in <i>MODE/SYNC Pin Control</i>	13
• Updated <i>Inductor Selection</i> guidance to include recommended design margins for subharmonic stability.....	21

Changes from Revision B (June 2026) to Revision C (August 2026)
Page

- Changed orderable part number PLMR604405SRBMRQ1 from preview status to LMR604405SRBMRQ1 release status in the *Device Comparison Table* **3**

Changes from Revision A (March 2026) to Revision B (June 2026)
Page

- Added more pin compatible devices to the *Features* list..... **1**
- Added MINT 1 switcher terminology to the document title, *Features* list, and *Description* **1**
- Changed orderable part numbers from preview status to release status in the *Device Comparison* table..... **3**
- Added PLMR604405SRBMRQ1 as Advance Information device to the *Device Comparison* table..... **3**
- Updated *Thermal Information* table to include RBM package metrics..... **5**
- Updated *Soft Start and Recovery from Dropout* to clarify the section for recovery from dropout..... **12**
- Updated SYNC mode description to clarify the external clock frequency range in [Section 7.3.4](#) **13**
- Added recommended layout example for RBM package..... **34**

Changes from Revision B (December 2025) to Revision C (July 2026)
Page

- Added more pin compatible devices to the *Features* list..... **1**
- Added MINT 1 switcher terminology in the document title, *Features* list, and *Description* **1**
- Changed release status for LMR604603SVBCRQ1 from APL to RTM (Release to Market)..... **3**
- Updated [Soft Start and Recovery from Dropout](#) to clarify the section for recovery from dropout..... **12**
- Updated SYNC mode description to clarify the external clock frequency range in [MODE/SYNC Pin Control](#) **13**

The datasheet number will be changing.

Device Family	Change From:	Change To:
LMR60410-Q1	SNAS870B	SNAS870C
LMR60406-Q1	SNAS871A	SNAS871B
LMR60430-Q1	SNAS875B	SNAS875E
LMR61440-Q1	SLVSK23	SLVSK23A
LMR60440-Q1	SNAS874A	SNAS874C
LMR60460-Q1	SNAS894B	SNAS894C

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/LMR60410-Q1>

<http://www.ti.com/product/LMR60406-Q1>

<http://www.ti.com/product/LMR60430-Q1>

<http://www.ti.com/product/LMR61440-Q1>

<http://www.ti.com/product/LMR60440-Q1>

<http://www.ti.com/product/LMR60460-Q1>

Reason for Change:

To accurately reflect device characteristics

Anticipated impact on Form, Fit, Function, Quality or Reliability:

None

Changes to product identification resulting from this PCN:

None

Products Affected:

LMR604063SBRAKRQ1	LMR604065SRAKRQ1	LMR604103SRAKRQ1
LMR604105SBRAKRQ1	LMR604105SRAKRQ1	LMR604303SBRAKRQ1
LMR604303SRAKRQ1	LMR604305SRAKRQ1	LMR604304SBRAKRQ1
LMR604305SBRAKRQ1	LMR604403SBRAKRQ1	LMR614403SRAKRQ1
LMR604404SBRAKRQ1	LMR604405SBRAKRQ1	LMR604403SRBMRQ1
LMR604605SVBCRQ1		

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

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